

**Dual P-Ch 20V Fast Switching MOSFETs**
**Description**

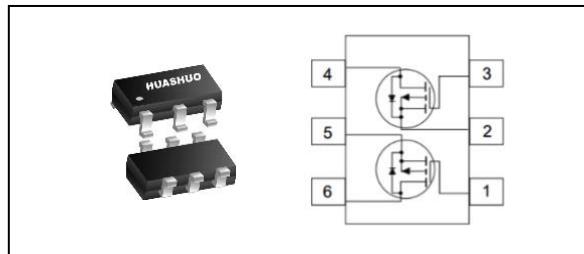
The HSW6811 is the high cell density trenched P-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

The HSW6811 meet the RoHS and Green Product requirement with full function reliability approved.

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**Product Summary**

V <sub>DS</sub>	-20	V
R <sub>DS(ON),typ</sub>	115	mΩ
I <sub>D</sub>	-2	A

**SOT23-6L Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sub>1</sub>	-2	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sub>1</sub>	-1.4	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	-8	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sub>3</sub>	1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sub>1</sub>	---	125	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sub>1</sub>	---	80	°C/W

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**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

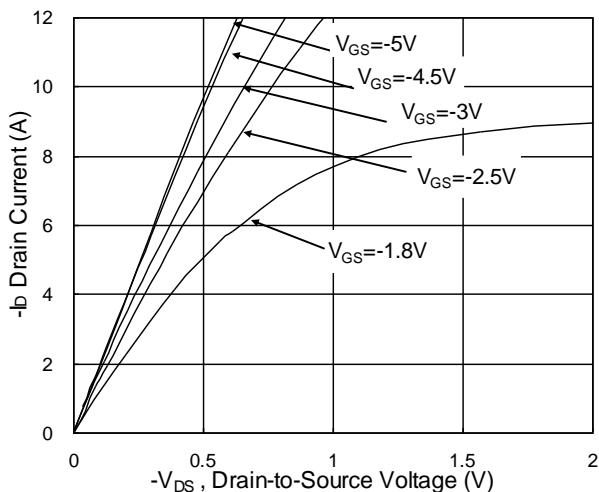
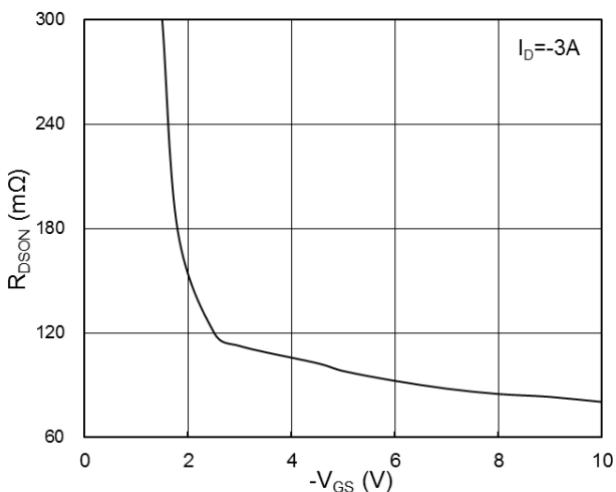
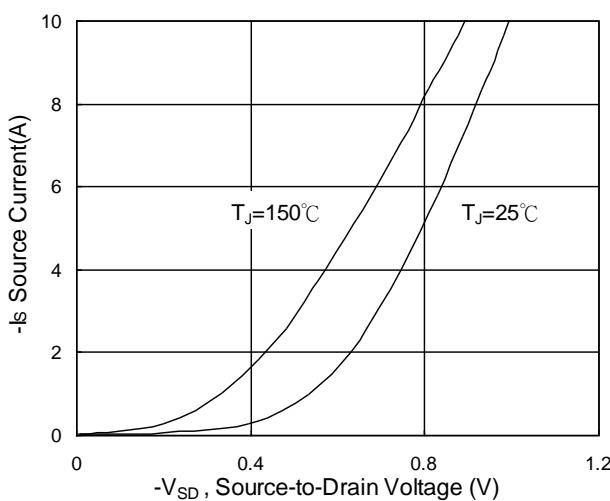
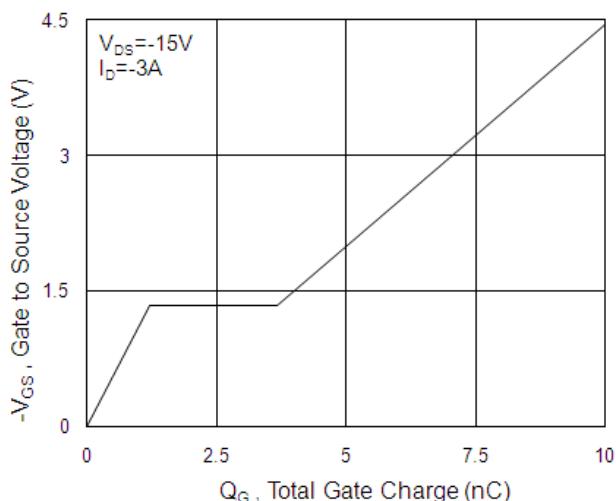
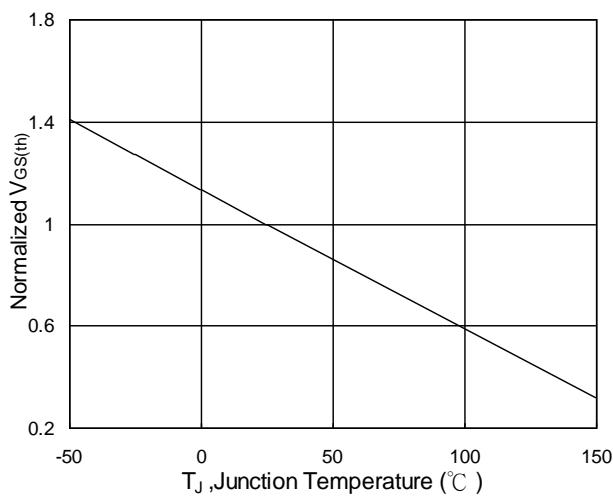
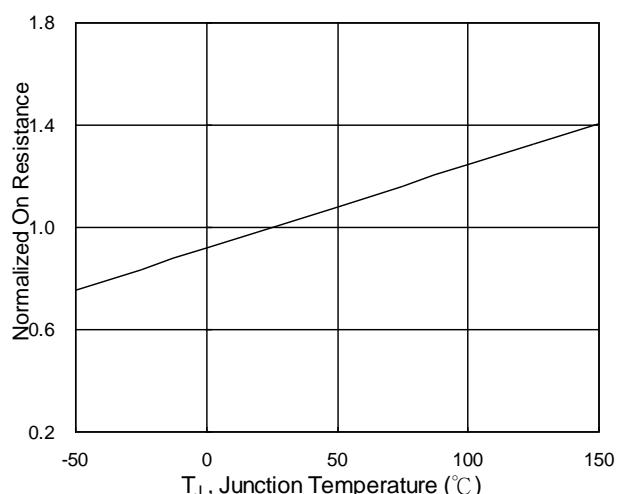
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250μA	-20	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sub>2</sub>	V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-2A	---	115	130	mΩ
		V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-1A	---	150	180	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	-0.5	-0.65	-1.0	V
I <sub>bss</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	-5	
I <sub>GS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±12V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-1A	---	5	---	S
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-2A	---	4.3	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	0.8	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	1	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-10V , V <sub>GS</sub> =-4.5V , R <sub>G</sub> =1Ω I <sub>D</sub> =-2A	---	12	---	ns
T <sub>r</sub>	Rise Time		---	20	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	24	---	
T <sub>f</sub>	Fall Time		---	9	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-10V , V <sub>GS</sub> =0V , f=1MHz	---	280	---	pF
C <sub>oss</sub>	Output Capacitance		---	54	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	44	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sub>1,4</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-2	A
V <sub>SD</sub>	Diode Forward Voltage <sub>2</sub>	V <sub>GS</sub> =0V , I <sub>s</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs. G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



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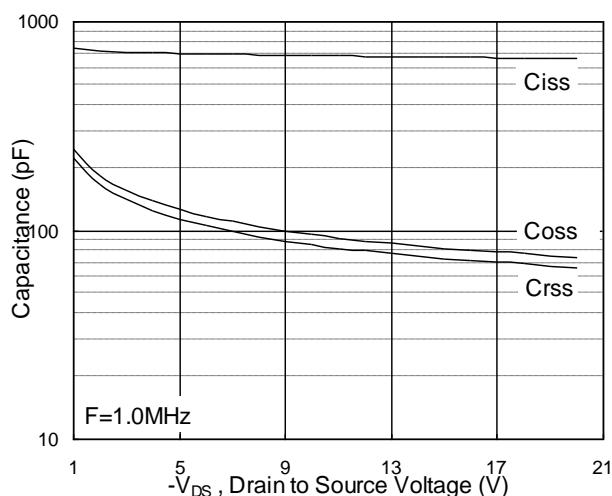


Fig.7 Capacitance

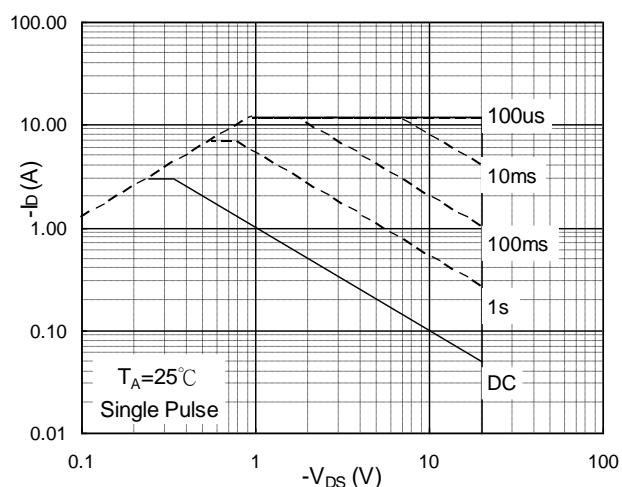


Fig.8 Safe Operating Area

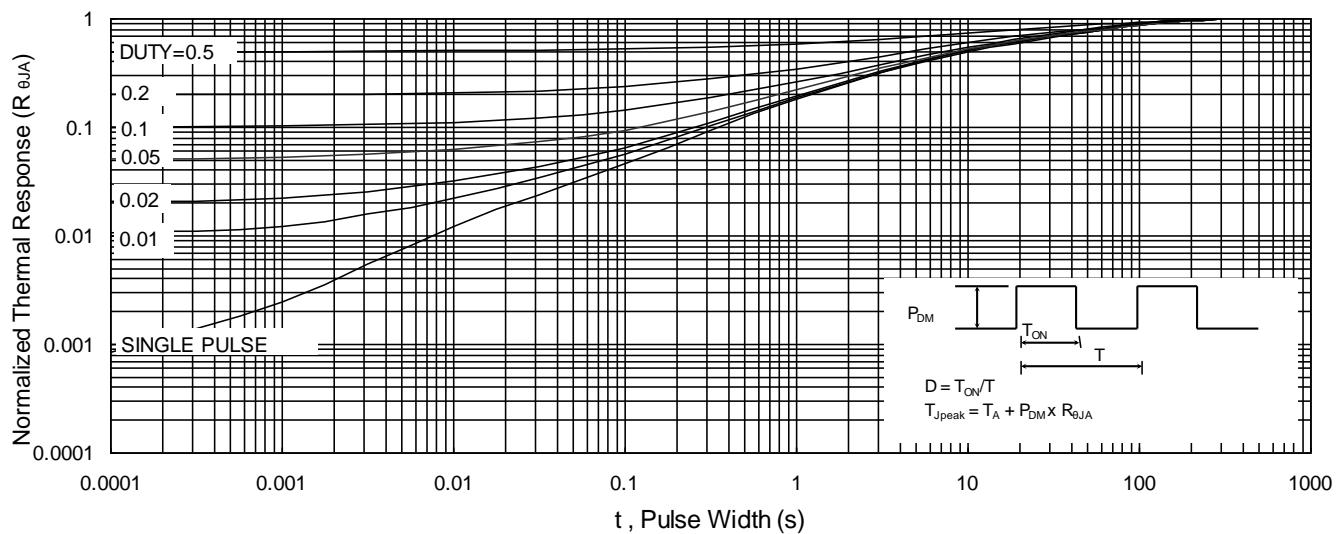


Fig.9 Normalized Maximum Transient Thermal Impedance

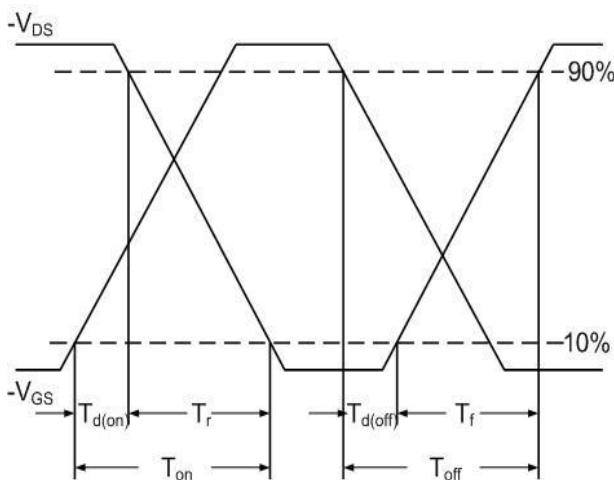


Fig.10 Switching Time Waveform

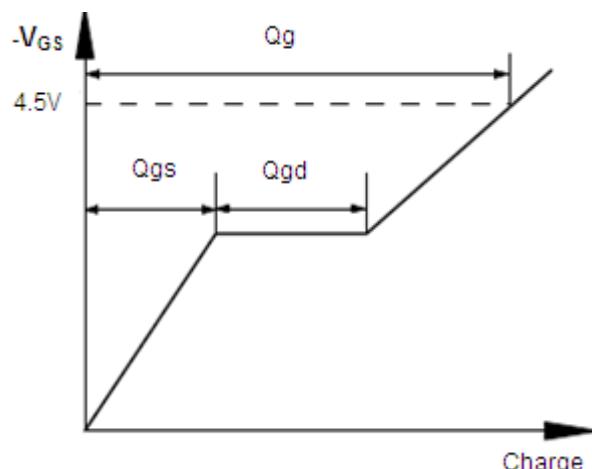
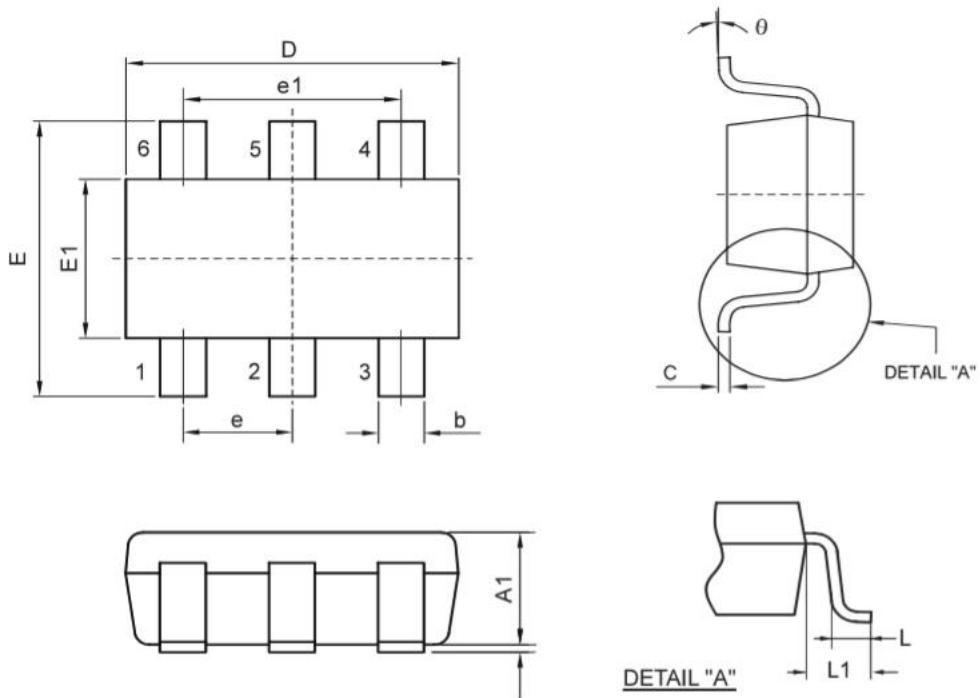


Fig.11 Gate Charge Waveform



## SOT23-6L Package Outline Dimensions



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	2.692	3.099	0.106	0.122
E	2.591	3.000	0.102	0.118
E1	1.397	1.803	0.055	0.071
e	0.950 REF.		0.037 REF.	
e1	1.900 REF.		0.075 REF.	
b	0.300	0.500	0.012	0.020
C	0.080	0.200	0.003	0.008
A	0.000	0.100	0.000	0.004
A1	0.700	1.200	0.028	0.048
L	0.300	0.600	0.012	0.024
L1	0.600 REF.		0.023 REF.	
θ	0°	9°	0°	9°

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